

FDP5680/FDB5680

60V N-Channel PowerTrench™ MOSFET

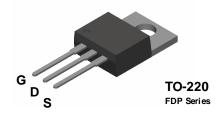
General Description

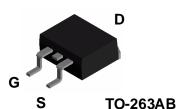
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

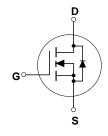
These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable $R_{{\rm DS(on)}}$ specifications resulting in DC/DC power supply designs with higher overall efficiency.

Features

- 40 A, 60 V. R $_{\rm DS(ON)}$ = 0.020 Ω @ V $_{\rm GS}$ = 10 V $_{\rm RDS(ON)}$ = 0.023 Ω @ V $_{\rm GS}$ = 6 V.
- Critical DC electrical parameters specified at evevated temperature.
- Rugged internal source-drain diode can eliminate the need for an external Zener diode transient suppressor.
- High performance trend technology for extremely low $R_{_{DS(ON)}}.$
- 175°C maximum junction temperature rating.







FDB Series

Absolute Maximum Ratings T_C = 25°C unless otherwise noted

| Symbol | Parameter | FDP5680 | FDB5680 | Units |
|-----------------------------------|--|---------|---------|-------|
| V _{DSS} | Drain-Source Voltage | (| V | |
| V _{GSS} | Gate-Source Voltage | ± | 20 | V |
| I _D | Maximum Drain Current - Continuous | 4 | А | |
| | - Pulsed | 1 | 1 | |
| P _D | Total Power Dissipation @ T _C = 25°C | (| W | |
| | Derate above 25°C | 0. | W/°C | |
| T _J , T _{STG} | Operating and Storage Junction Temperature Range | -65 to | +175 | °C |

Thermal Characteristics

| R _e JC | Thermal Resistance, Junction-to-Case | 2.3 | °C/W |
|-------------------|---|------|------|
| R _{oJA} | Thermal Resistance, Junction-to-Ambient | 62.5 | °C/W |

Package Marking and Ordering Information

| Device Marking | Device | Reel Size | Tape Width | Quantity |
|----------------|---------|-----------|------------|----------|
| FDB5680 | FDB5680 | 13" | 24mm | 800 |
| FDP5680 | FDP5680 | Tube | N/A | 45 |

| Symbol | Parameter | Test Conditions | Min | Тур | Max | Units |
|-------------------------------------|---|---|-----|-------------------------|-------------------------|-------|
| Drain-So | urce Avalanche Ratings (No | ote1) | | | | |
| W _{DSS} | Single Pulse Drain-Source Avalanche Energy | V _{DD} = 30 V, I _D = 40A | | | 90 | mJ |
| I _{AR} | Maximum Drain-Source Avalanche | e Current | | | 40 | Α |
| Off Char | acteristics | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$ | 60 | | | V |
| <u>∆</u> BVdss ∆TJ | Breakdown Voltage Temperature Coefficient | I _D = -250 _{LL} A, Referenced to 25°C | | 60 | | mV/∘C |
| I _{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 48 \text{ V}, V_{GS} = 0 \text{ V}$ | | | 1 | μА |
| I _{GSSF} | Gate-Body Leakage Current, Forward | $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$ | | | 100 | nA |
| I _{GSSR} | Gate-Body Leakage Current, Reverse | $V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$ | | | -100 | nA |
| On Chara | acteristics (Note 1) | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$ | 2 | 2.5 | 4 | V |
| <u>Δ</u> VGS(th) ΔΤ _J | Gate Threshold Voltage Temperature Coefficient | $I_D = -250 \mu\text{A}$, Referenced to 25°C | | -6.4 | | mV/∘C |
| R _{DS(on)} | Static Drain-Source On-Resistance | $V_{GS} = 10 \text{ V}, I_D = 20 \text{ A},$ $V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}, T_J = 125 \circ \text{C}$ $V_{GS} = 6 \text{ V}, I_D = 19 \text{ A}$ | | 0.016 0.022 0.018 | 0.020 0.035 0.023 | Ω |
| I _{D(on)} | On-State Drain Current | V _{GS} = 10 V, V _{DS} = 5 V | 20 | | | Α |
| g _{FS} | Forward Transconductance | $V_{DS} = 5 \text{ V}, I_{D} = 20 \text{ A}$ | | 43 | | S |
| Dynamic | Characteristics | | | | | |
| C _{iss} | Input Capacitance | $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ | | 1850 | | pF |
| Coss | Output Capacitance | f = 1.0 MHz | | 230 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 95 | | pF |
| Switchin | g Characteristics (Note 1) | | | | | |
| $t_{d(on)}$ | Turn-On Delay Time | $V_{DD} = 30 \text{ V}, I_D = 1 \text{ A},$ | | 15 | 27 | ns |
| t _r | Turn-On Rise Time | $V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$ | | 9 | 18 | ns |
| t _{d(off)} | Turn-Off Delay Time | | | 35 | 56 | ns |
| t _f | Turn-Off Fall Time | | | 16 | 26 | ns |
| Q _g | Total Gate Charge | $V_{DS} = 30 \text{ V}, I_{D} = 20 \text{ A}$ | | 33 | 46 | nC |
| Q_{gs} | Gate-Source Charge | V _{GS} = 10 V | | 6.5 | | nC |
| Q_{gd} | Gate-Drain Charge | | | 7.5 | | nC |
| Drain-So | urce Diode Characteristics | and Maximum Ratings | | | | |
| I _s | Maximum Continuous Drain-Source | | | | 40 | Α |
| V _{SD} | Drain-Source Diode Forward Voltage | $V_{GS} = 0 \text{ V}, I_S = 20 \text{ A}$ (Note 1) | | 0.9 | 1.2 | V |

^{1.} Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%

Typical Characteristics

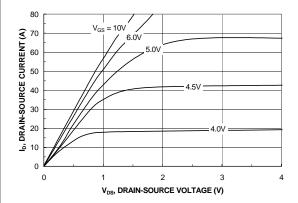


Figure 1. On-Region Characteristics.

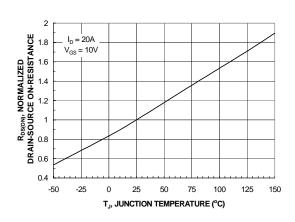


Figure 3. On-Resistance Variation with Temperature.

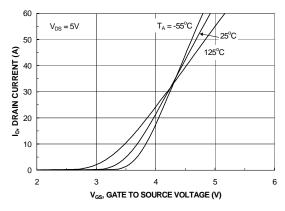


Figure 5. Transfer Characteristics.

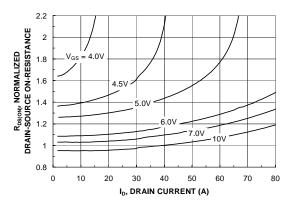


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

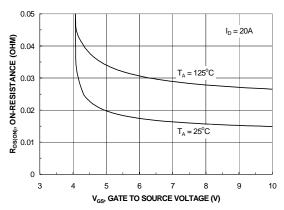


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

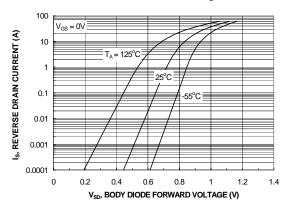
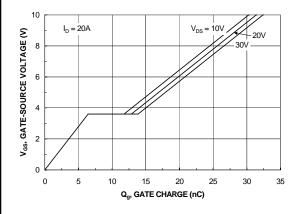


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.





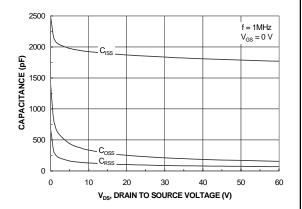
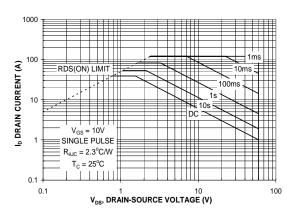


Figure 7. Gate-Charge Characteristics.





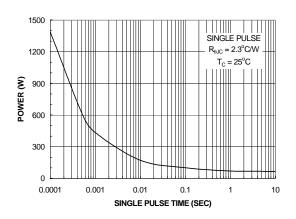


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

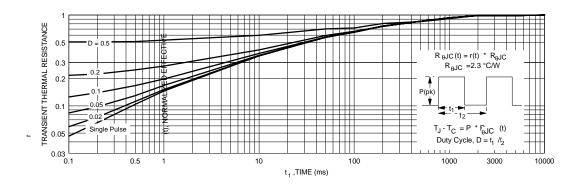
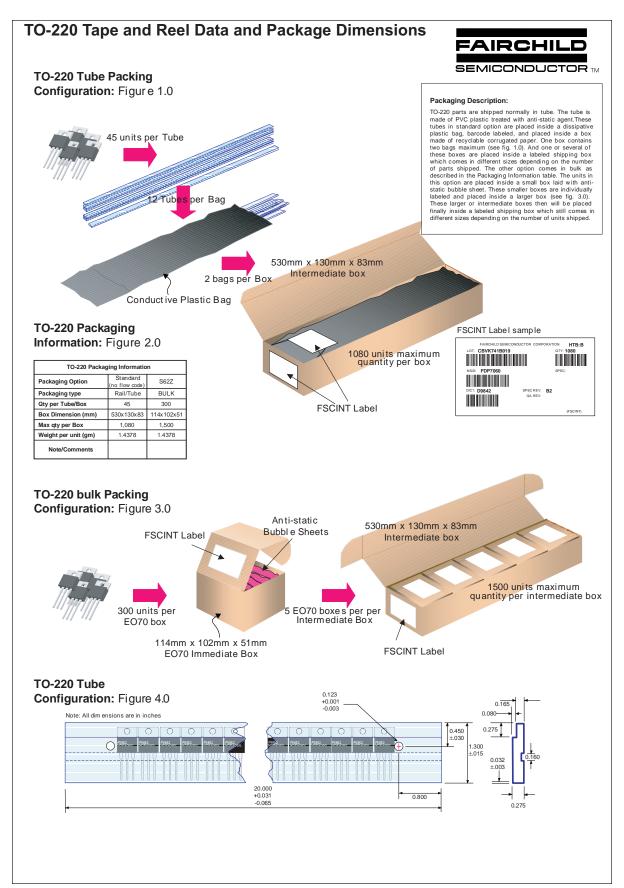
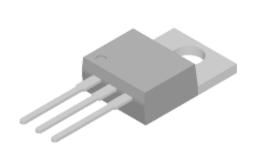


Figure 11. Transient Thermal Response Curve.

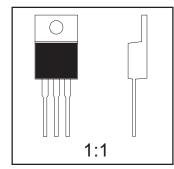


TO-220 Tape and Reel Data and Package Dimensions, continued

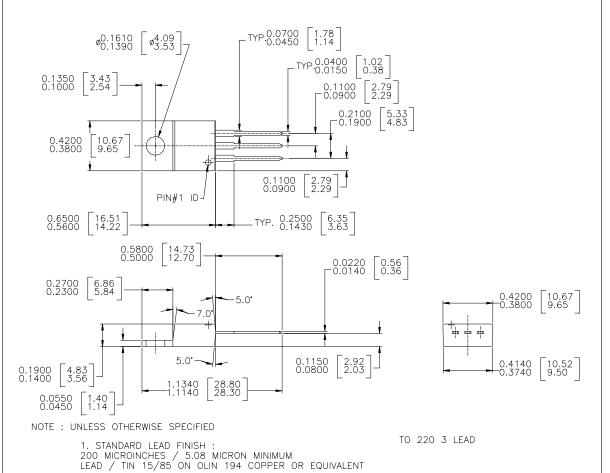
TO-220 (FS PKG Code 37)

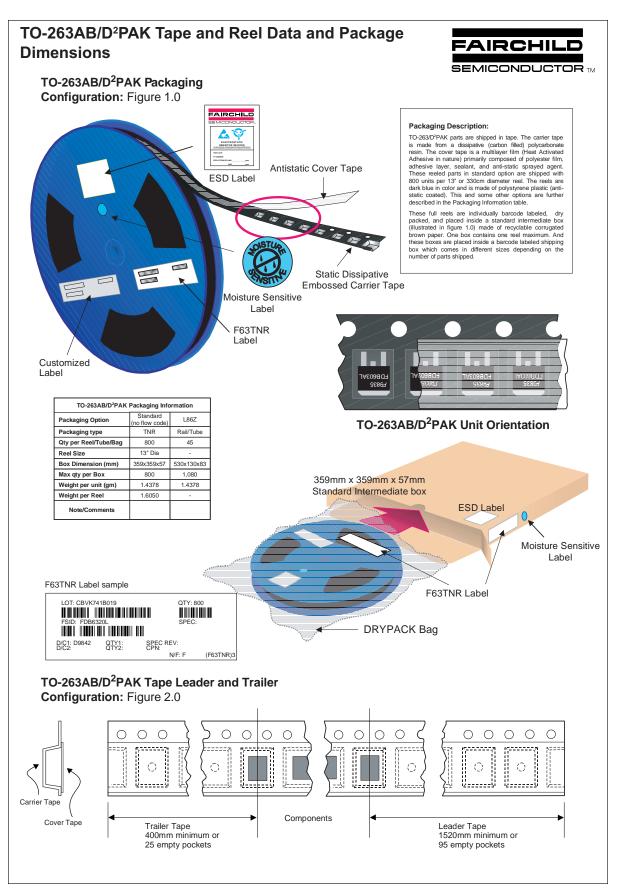


2. DIMENSION BASED ON JEDEC STANDARD TO-220 VARIATION AB, ISSUE J, DATED 3/24/87

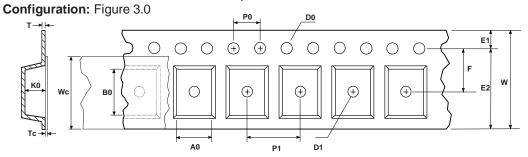


Scale 1:1 on letter size paper
Dimensions shown below are in:
inches [millimeters]





TO-263AB/D²PAK Embossed Carrier Tape



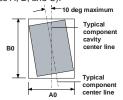
User Direction of Feed

| | Dimensions are in millimeter | | | | | | | | | | | | | |
|-----------------------------|------------------------------|------------------|----------------|-----------------|-----------------|-----------------|--------------|------------------|----------------|---------------|-----------------|-------------------|----------------|-----------------|
| Pkg type | Α0 | В0 | w | D0 | D1 | E1 | E2 | F | P1 | P0 | K0 | Т | Wc | Тс |
| TO263AB/ D²PAK (24mm) | 10.60 +/-0.10 | 15.80 +/-0.10 | 24.0 +/-0.3 | 1.55 +/-0.05 | 1.60 +/-0.10 | 1.75 +/-0.10 | 22.25 min | 11.50 +/-0.10 | 16.0 +/-0.1 | 4.0 +/-0.1 | 4.90 +/-0.10 | 0.450 +/-0.150 | 21.0 +/-0.3 | 0.06 +/-0.02 |

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation

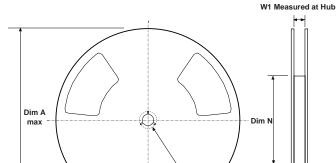


Sketch B (Top View)
Component Rotation

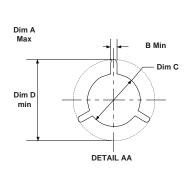


Sketch C (Top View)
Component lateral movement

TO-263AB/D²PAK Reel Configuration: Figure 4.0







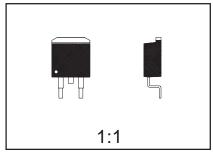
W2 max Measured at Hub

See detail AA

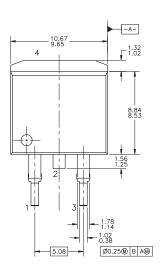
| Dimensions are in inches and millimeters | | | | | | | | | |
|--|----------------|--------------|--------------|-----------------------------------|---------------|-------------|----------------------------------|---------------|--------------------------------|
| Tape Size | Reel Option | Dim A | Dim B | Dim C | Dim D | Dim N | Dim W1 | Dim W2 | Dim W3 (LSL-USL) |
| 24mm | 13" Dia | 13.00 330 | 0.059 1.5 | 512 +0.020/-0.008 13 +0.5/-0.2 | 0.795 20.2 | 4.00 100 | 0.961 +0.078/-0.000 24.4 +2/0 | 1.197 30.4 | 0.941 - 0.1.079 23.9 - 27.4 |

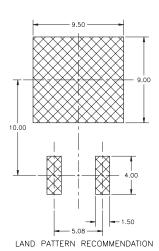
TO-263AB/D²PAK (FS PKG Code 45)

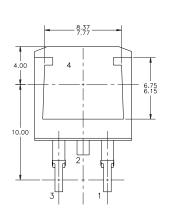


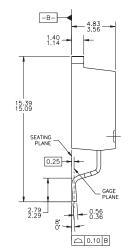


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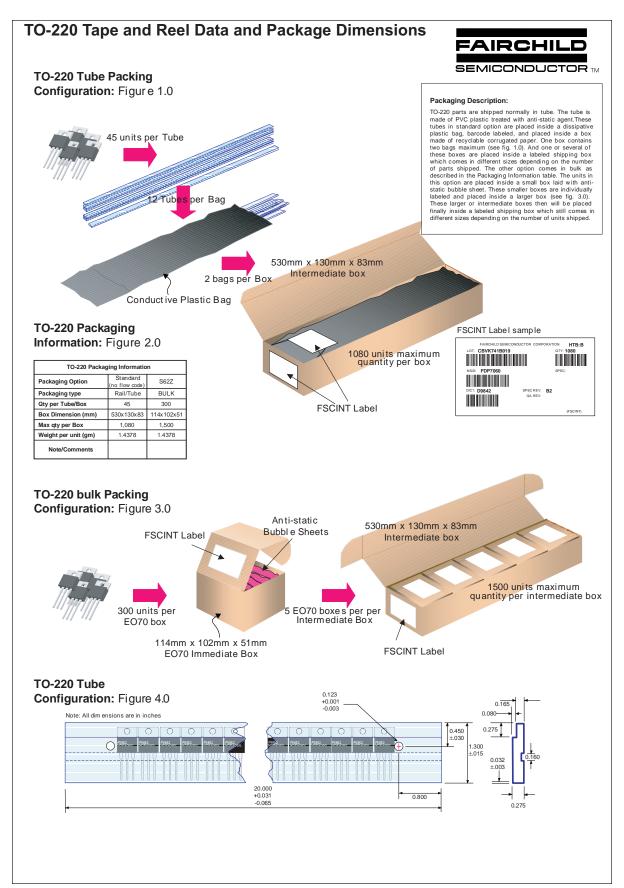
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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

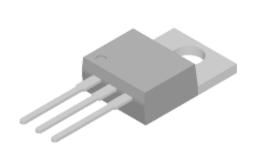
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|--------------------------|---------------------------|---|
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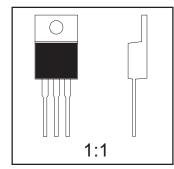


TO-220 Tape and Reel Data and Package Dimensions, continued

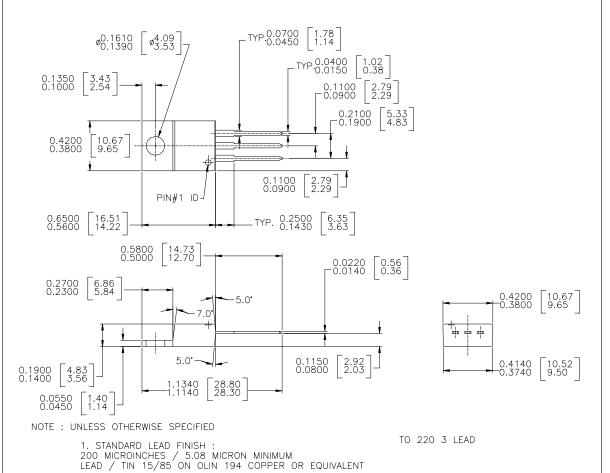
TO-220 (FS PKG Code 37)

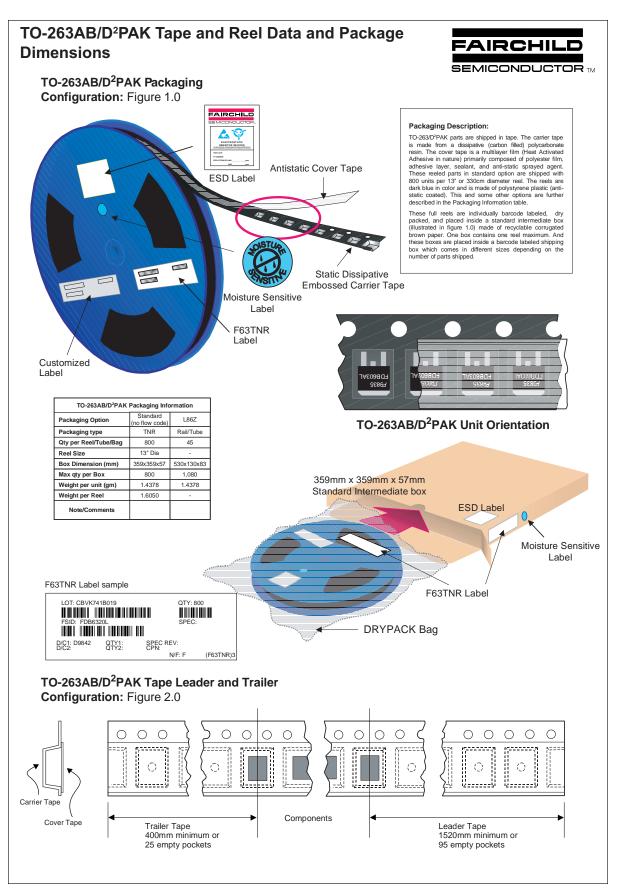


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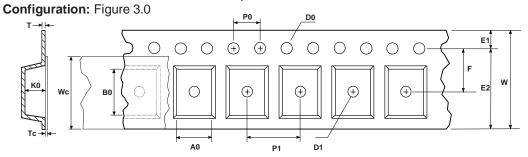


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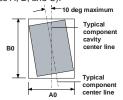
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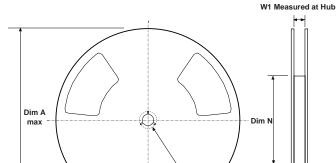


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Component Rotation

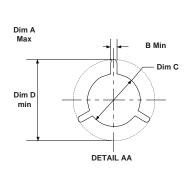


Sketch C (Top View)
Component lateral movement

TO-263AB/D²PAK Reel Configuration: Figure 4.0







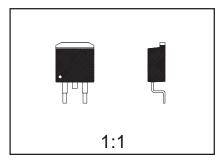
W2 max Measured at Hub

See detail AA

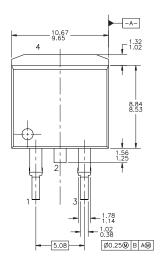
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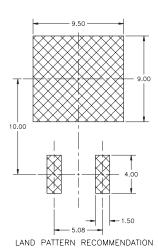
TO-263AB/D²PAK (FS PKG Code 45)

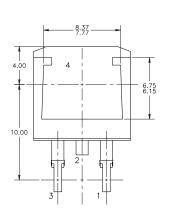


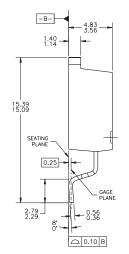


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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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